

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free):   XC9503xxxxDR-G  
Typical Mass:           12     mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	1.194	Silicon	99500	7440-21-3
	-	Arsenic	6	7440-38-2
Lead pad	2.287	Nickel	190600	7440-02-0
	0.104	Silver	8700	7440-22-4
	0.023	Gold	1900	7440-57-5
Die attach	0.064	Silver	5300	7440-22-4
	0.017	Epoxy Resin	1400	—
	0.004	Phenol Resin	400	—
Bonding wire	0.118	Gold	9800	7440-57-5
Resin	7.166	Silica	597100	60676-86-0
	0.409	Epoxy Resin	34100	—
	0.369	Phenol Resin	30700	—
	0.245	Metal Hydroxide	20400	—

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."